



FOR IMMEDIATE RELEASE

EV GROUP WINS MULTI-MILLION-EURO ORDER FROM LEADING EUROPEAN ELECTRONICS MANUFACTURER FOR HIGH-VOLUME PRODUCTION OF FLEXIBLE DISPLAYS

Company's Advanced Coating Tools to be Leveraged in Commercialization of Thinner, Lighter Portable Consumer Electronic Devices

ST. FLORIAN, AUSTRIA, January 16, 2008 – EV Group (EVG), a leading supplier of manufacturing equipment for the advanced packaging/3D interconnect, MEMS, SOI (silicon-on-insulator), nanotechnology, compound semiconductor and silicon-based power devices markets, today announced that it has received a multi-million-Euro order from a leading European plastic electronics manufacturer for the high-volume production of flexible displays. The multiple system order will be installed at the customer's facility between now and mid-2008, and leveraged in the development of flexible display modules used within thin, light and robust consumer electronics products, such as portable electronic readers.

Today's announcement is a key milestone for EVG as it demonstrates the successful deployment of EVG's advanced coating technology in the flexible display arena. Since 2004, EVG has been working closely with Arizona State University's Flexible Display Center (FDC) to leverage its advanced resist coating technology to address the burgeoning flexible display arena. The FDC, of which EVG is a principal member, is a university/industry/government collaborative venture chartered with developing high performance, commercially-viable, conformal and flexible displays that are lightweight, rugged, low power and low cost. Today's order from a leading plastics electronics maker underscores the tremendous development achievements realized between EVG and FDC's strong collaboration over the past few years.

The production of flexible displays pose myriad challenges, namely manufacturing equipment's ability to support flexible substrates, such as plastic, which lacks the mechanical and thermal stability typically afforded by the rigid and durable—yet unconformable—glass substrate. As a result, the fabrication of flexible displays places strict demands on processing equipment. EVG addresses these challenges with its advanced processing systems, which provide special handling capabilities for processing fragile substrates in varying size and thickness. High uptime and ease of maintenance contribute to increased performance and yield. Moreover, the tools' ability to produce highly uniform coats at low material usage and improved repeatability equate to a low cost of ownership. EVG reports that all of these advantages and performance capabilities, coupled with its comprehensive 24/7 service and support infrastructure, were critical factors behind this order win.

Commenting on today's announcement, Erich Thallner, CEO and founder of the EVG, noted, "We're constantly looking at new opportunities and markets that will let us leverage our proven workhorse technology to enter promising new markets. The flexible display market continues to make significant strides and EVG is proud to be at the forefront of helping drive this technology into mainstream adoption. Today's order is testament to our ability to help customers reduce the time and cost it takes to get products to market by delivering highly integrated systems and customized solutions that allow them to realize significant growth opportunities. Moreover, it shows the value of R&D collaboration and how, by working in tandem with customers and other industry partners, we can move from vision to market fruition—quickly and more cost effectively."

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About EV Group

EV Group (EVG) is a world leader in wafer-processing solutions for semiconductor, MEMS and nanotechnology applications. Through close collaboration with its global customers, the company implements its flexible manufacturing model to develop reliable, high-quality, low-cost-of-ownership systems that are easily integrated into customers' fab lines. Key products include wafer bonding, lithography/nanoimprint lithography (NIL) and metrology equipment, as well as photoresist coaters, cleaners and inspection systems.

In addition to its dominant share of the market for wafer bonders, EVG holds a leading position in NIL and lithography for advanced packaging and MEMS. Along these lines, the company co-founded the EMC-3D consortium in 2006 to create and help drive implementation of a cost-effective through-silicon via (TSV) process for chip packaging and MEMS/sensors. Other target semiconductor-related markets include silicon-on-insulator (SOI), compound semiconductor and silicon-based power-device solutions.

Founded in 1980, EVG is headquartered in St. Florian, Austria, and operates via a global customer support network, with subsidiaries in Tempe, Ariz.; Albany, N.Y.; Yokohama and Fukuoka, Japan; and Chung-Li, Taiwan. The company's vertical infrastructure allows EVG to respond quickly to new technology developments, apply the technology to manufacturing challenges and expedite device manufacturing in high volume. More information is available at www.evgroup.com.

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